

Product	Laser diode
Package	RLD65MQX1

Materials	Flow chart			Name of process	Used equipment & machine	Controlled item
	Material acceptance	Preparatory process	Main Process			
LD chip	<pre> graph TD     A[Material Acceptance] --&gt; B{1}     B --&gt; C((2))     C --&gt; D{3}     D --&gt; E((4))     E --&gt; F((5))     F --&gt; G{6}     G --&gt; H((7))     H --&gt; I{8}     I --&gt; J((9))           </pre>			Acceptance test	Visual	Appearance
Submount				Chips preparation	Braking machine Expander	Appearance Air pressure Temperature
				Acceptance test	Microscope	Appearance
				Die-&wire-bonding(1)	ALDW40	Temperature DB load Ultrasonic power WB load
				Measurement	ALDW40	Probe state I-L characteristics I-V characteristics
Stem				Inspection(1)	Tension gauge	Wire-pull resistivity Peel-off resistivity
Bonding agent				Die-&wire-bonding(2)	ASDW	Temperature DB load Ultrasonic power
				Inspection(2)	Microscope Tension gauge FFP standard Correct monitorscope	Wire-pull resistivity DB load Facet inclination $\Delta$ XYZ
Cap				Can sealing	AACL	Air pressure N2 pressure Humidity

Materials	Flow chart			Name of process	Used equipment & machine	Controlled item
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			10	Inspection for sealing	Cutting nipper Micrometer Correct monitorscope	Weld strength Weld extrusion Degree of decentering
			11	Products burn-in test	AATB	Set temperature I-L characteristics (100% test)
			12	Final measurement Marking	ATMS	Temperature I-L characteristics I-V characteristics Positional accuracy FFP Wavelength Appearance (100% test)
			13	Appearance check	Microscope	Crazing and dirt of lens Flaws of stem In deposition (100% test)
			14	Quantity treatment	Calculator	Quantity check
			15	Packing		Slip Indication check
			16	Shipment inspection		Outer label and contents check
			17	Packaging		Detailed statement for shipment Packing condition
			18	Shipment		

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